



**TROQ Electronic Co.,Ltd.**  
**CRYSTAL UNIT SPECIFICATIONS**

<b>Customer</b>	
<b>Production Name</b>	<b>SMD CRYSTAL GLASS 5.0*3.2 2PIN</b>
<b>Customer P/N</b>	<b>N/A</b>
<b>TROQ P/N</b>	<b>RG30000243</b>
<b>Revision</b>	<b>A</b>
<b>Print Date</b>	<b>2023/5/11</b>

<b>Drawn</b>	<b>Checked</b>	<b>Approved</b>

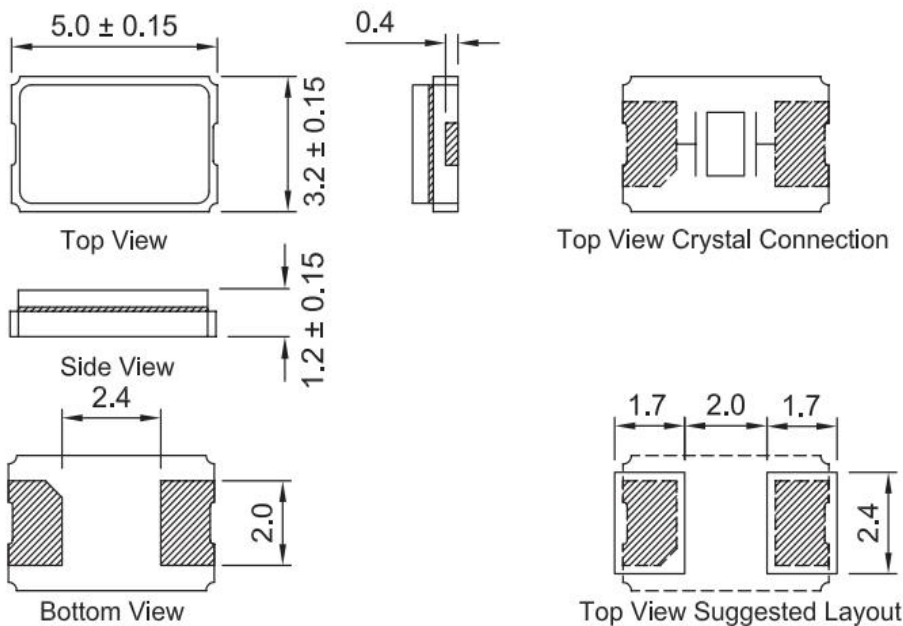


RoHS Compliant

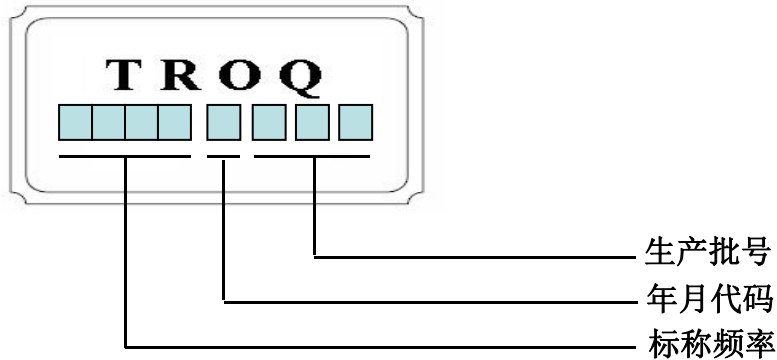
● ELECTRICAL PARAMETERS

谐振器产品技术指标	Min	Max	Units
1.Holder Type(型号规格)	GLASS 5.0*3.2 2PIN		
2.Mode of Oscillation (振动模式)	Fundamental		
3.Frequency (标称频率)	30.000000		MHz
4.Load Capacitance (CL) (负载电容)	20		pF
5.Shunt Capacitance (Co) (静态电容)	1	7	pF
6.Equivalent Resistance (谐振电阻)		50	Ω
7.Frequency Tolerance at 25°C (调整频差)	-20	20	ppm
8.Stability over operation temperance (温度频差)	± 20		ppm
9.Insulation Resistance (at DC 100V) (绝缘电阻)	500		MΩ
10.Drive Level (激励功率)	100		uw
11.Operating Temperature Range (工作温度范围)	-20	70	°C
12. Storage Temperature Range (储存温度范围)	-40	85	°C
13. Aging (老化率)	± 2		ppm/year
14.Other(其它)	N/A		

OUTLINE DIMENSIONS(UNIT:mm) 外形尺寸 (单位: mm)



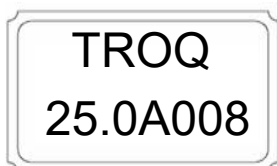
● Marking (标记)



● 年月代码

2020月份	1	2	3	4	5	6	7	8	9	10	11	12
2020年月码	A	B	C	D	E	F	G	H	J	K	L	M
2021月份	1	2	3	4	5	6	7	8	9	10	11	12
2021年月码	N	P	Q	R	S	T	U	V	W	X	Y	Z
2022月份	1	2	3	4	5	6	7	8	9	10	11	12
2022年月码	a	b	c	d	e	f	g	h	j	k	l	m
2023月份	1	2	3	4	5	6	7	8	9	10	11	12
2023年月码	n	p	q	r	s	t	u	v	w	x	y	z

注：以上年月代码每四年一个循环。



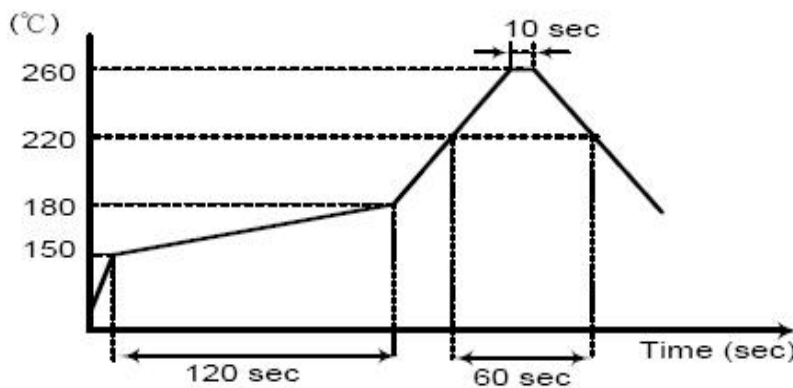
→ 说明：标称频率 25.000MHZ  
2020年1月份制造，生产批号为008  
上述产品标志从2012年7月1日正式执行



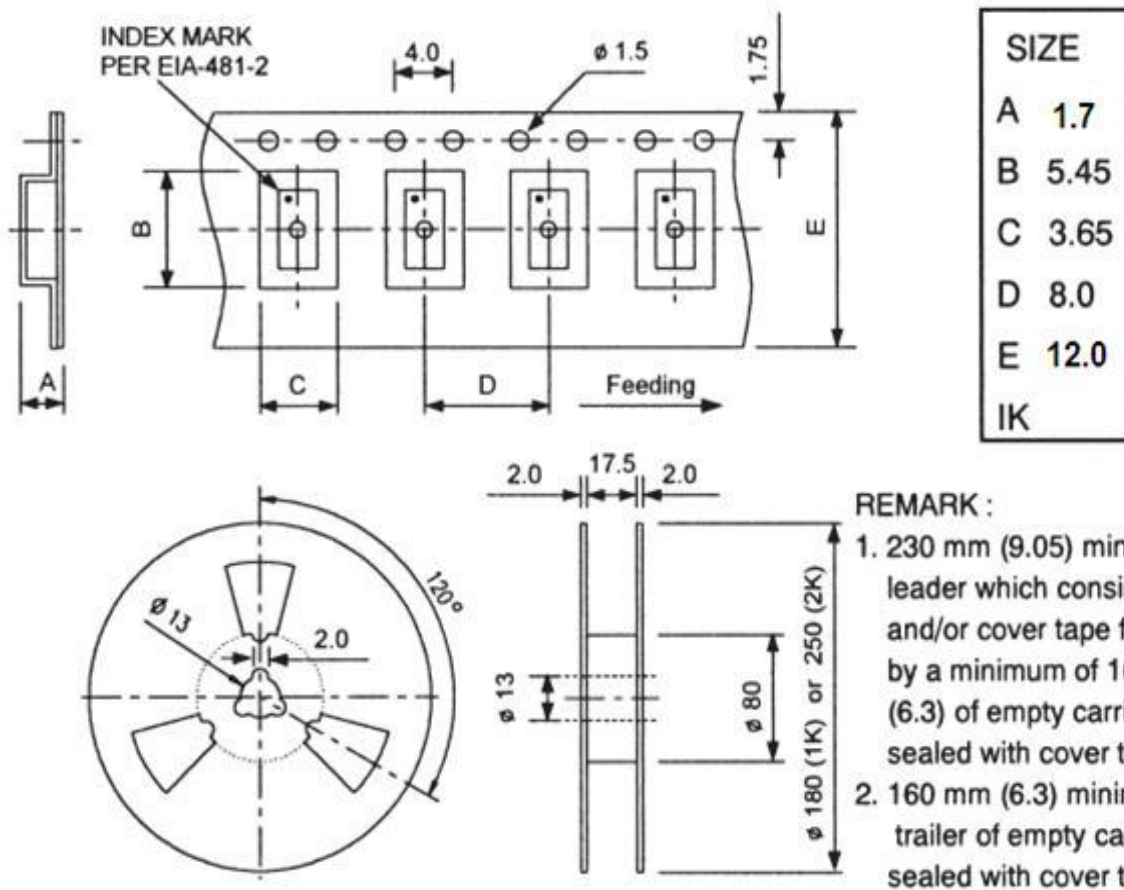
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- **SUGGESTED REFLOW PROFILE** (回流焊曲线图)  
**Total time:200sec.Max.** (总时间: 200秒 最大)  
**Solder melting point:220℃** (熔点220℃)

Profiles Feature (特性)		Pb-Free Assembly
Average Ramp-up Rate(Ts max to Tp)	平均升温速度	3°C/second Max
Preheat	预热	
■ Temperature Min (Ts min)	最低温度	125°C
■ Temperature Max (Ts max)	最高温度	200°C
■ Time (ts min to ts max)	从最低到最高时间	(60~180) seconds
Time maintained above	维持上述时间	
■ Temperature(T1)	温度	217°C
■ Time(tp)	时间	(60~150) seconds
Peak/Classification Temperature(Tp)	最高点温度	260 °C
Time within 5°C of actual Peak Temperature(tp)	高温维持时间	(20~40) seconds
Ramp-down rate	降温速度	6°C/second max
Time 25°C to Peak Temperature	从25°C到最高温度的时间	8 minutes max
Suggest reflow times	建议 reflow次数	3 Times max



● PACKING (包装) 1Kpcs/REEL



● RELIABILITY SPECIFICATIONS (信赖度试验)

No	Test Item (测试项目)	Test Conditions (测试条件)	Reference (参考)
1	High Temperature High Humidity Storage (高温、高湿、储存)	Temperature: 85°C±3°C 温度: 85°C±3°C Relative Humidity:85%RH 相对湿度: 85%RH Time: 96 Hours 时间: 96小时	JIS C5023
2	High Temperature Storage (高温储存)	Temperature: 125°C±3°C 温度:125°C±3°C Time: 96 Hours 时间:96 小时	MIL-STD-883E Method 1005.8
3	Low Temperature Storage (低温储存)	Temperature: -40°C±3°C 温度: -40°C±3°C Time: 96Hours 时间: 96小时	MIL-STD-883E Method 1013
4	Thermal Shock (温度冲击)	Temperature1:-55°C±5°C 温度1:-55°C±5°C Temperature2:85°C±5°C 温度2: 85°C±5°C Temperature change between T1 and T2 5 min T1和T2温度在5分钟内改变 10cycles maintain T1 and T2 for 30 minutes each mone cycle 每次循环30分钟共10次	MIL-STD-202F Method 107 Condition A
5	RESISTANCE TO SOLDER HEAT (耐焊接热)	Solder Temperature: 260°C±5°C 焊槽温度:260°C±5°C Time: 10±1 Seconds 时间: 10±1秒	MIL-STD-202F Method 210E
6	Solderability(可焊性)	The solder pot temperature is 245±5°C , dwell time 5±0.5 245±5°C焊锡槽浸润5±0.5秒	J-STD-002B
7	Drop Test (落下试验)	3 Times Free Fall from 50cm height table to 3cm thickness hard wood board 从50cm高度3次跌落到3cm厚硬质木板上	JIS C6701
8	MECHANICAL SHOCK (机械冲击)	Half sine wave,1000 G 半正弦波,加速度1000G 3 Times for all 3 directions X、Y、Z 三个相互垂直方向各三次	MIL-STD-202F Method 213B
9	Vibration (机械振动)	Frequency Range: 10Hz~55Hz 频率范围: 10Hz~55Hz Amplitude: 0.75mm 振幅: 0.75mm 2 Hours in each direction, total 6 Hours X、Y、Z 三个相互垂直方向各振动2小时	MIL-STD-883E Method 2007.3
10	Leakage Test (气密性)	Take measurements with a helium Leakage detector 氦质检漏 Leakage Rate≤1×10 <sup>-3</sup> Pa cm <sup>3</sup> /s 漏率≤1×10 <sup>-3</sup> Pa cm <sup>3</sup> /s	MIL-STD-883E